6-104068-0 ✔ ACTIVE

AMPMODU | AMPMODU System 50

TE Internal #: 6-104068-0

PCB Mount Header, Vertical, Board-to-Board, 16 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold (Au), AMPMODU System 50

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: **PCB Mount Header**

Connector System: **Board-to-Board**

Number of Positions: **16**

Number of Rows: **2**

Centerline (Pitch): **1.27 mm [.05 in]**

Features

Product Type Features

PCB Connector Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly

Configuration Features

Connector Contact Load Condition	Fully Loaded
Number of Positions	16
Number of Rows	2
PCB Mount Orientation	Vertical
Board-to-Board Configuration	Parallel

Electrical Characteristics

Operating Voltage	30 VAC
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	500 VAC

Body Features

Connector Profile	Standard

Primary Product Color	Black

Contact Features

Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material Finish	Matte
Mating Square Post Dimension	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 µm[150 – 250 µin]
Contact Shape & Form	Rectangular
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material Thickness	.76 µm[30 µin]
Contact Mating Area Plating Material	Gold (Au)
Contact Type	Pin
Contact Current Rating (Max)	3.6 A

Termination Features

Termination Post & Tail Diameter	.38 mm[.015 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to PCB	Through Hole - Solder

Mechanical Attachment

Mating Retention Type	Latch
Mating Retention	With
Mating Alignment Type	Polarization
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	Without

Housing Features

Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	Liquid Crystal Polymer (LCP)

Dimensions

Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]

Usage Conditions

Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]

Operation/Application

Solder Process Feature	Board Standoff
Circuit Application	Signal

Industry Standards

Compatible With Agency/Standards Products	CSA, UL
UL Rating	Recognized
Compatible With Approved Standards Products	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Quantity	31
Packaging Method	Box, Tube

Other

Position Locations Omitted	0

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	有害物质含量符合标准要求 No Restricted Substance(s) Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2025 (250) Candidate List Declared Against: JUNE 2025 (250) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products

will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



TE Part # 487924-8
016 HOUSING FFC RCPT 50CL DR



TE Part # 6-104078-1
16 SYSTEM 50 RCPT ASSY DRST SN



TE Part # 2-111196-7
016 RCPT SYSTEM 50 30 DPLX

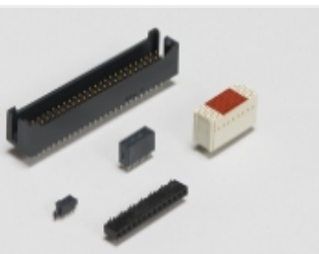


TE Part # 1-487937-6
016 HOUSING FFC 50CL DR LATCH

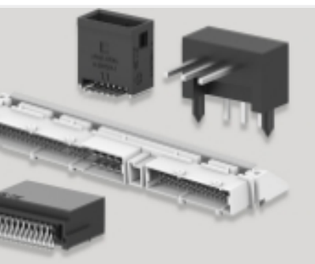


TE Part # 1-487938-6
016 HOUSING FFC 50CL DR

Also in the Series | AMPMODU System 50



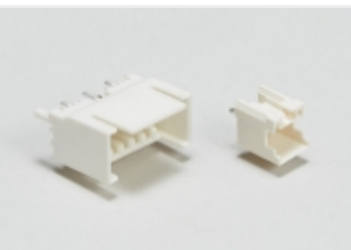
Board-to-Board Headers & Receptacles(218)



PCB Headers & Receptacles(218)



Rectangular Power Connectors(31)



Wire-to-Board Headers & Receptacles (31)

Customers Also Bought



TE Part #T4131512051-000
M12,REAR MOUNT,FEMALE,D,5P, SOLDER WIRE



TE Part #5-103765-3
03 MODII HD SRRA B/A .100CL,LF



TE Part #5-104068-1
20 SYSTEM 50 HDR DRST SHRD



TE Part #6-104069-2
24 sys 50 hdr drra shrd sn



TE Part #5-104071-1
10 SYSTEM 50 HDR SRST SHRD SN



TE Part #487545-7
010 HOUSING FFC RCPT 050CL SR



TE Part #2-487937-4
024 HOUSING FFC 50CL DR LATCH



TE Part #2-1462041-5
IMB03ITS=IM RELAY 140mW 5V



PITCH BATTERY



TE Part #2016677-4
RF CA,UMCC GEN2-GEN4,0.81,L80, BLACK

Documents

Product Drawings

16 SYSTEM 50 HDR DRST SHRD

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_6-104068-0_S.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_6-104068-0_S.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_6-104068-0_S.3d_stp.zip

English

By downloading the CAD file I accept and agree to the Terms and Conditions of use.

Datasheets & Catalog Pages

AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English

Ribbon Cable Interconnect Solutions

English

Product Specifications

Application Specification

English